Global Die Bonder Equipment Market Study 2015-2025, by Segment (Fully Automatic, Semi-Automatic, Manual), by Market (Integrated Device Manufacturers (IDMs), Outsourced Semiconductor Assembly and Test (OSAT)Semi-Automatic), by Company (Besi, ASM Pacific Technology (ASMPT), Kulicke & Soffa)

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Abstracts

SNAPSHOT

Die bonding is the process of attaching a die/chip to a substrate or package. Die bonding is accomplished by using one of the following processes: 1. Eutectic; 2. Solder; 3. Adhesive; 4. Glass or Silver-Glass

The global Die Bonder Equipment market will reach xxx Million USD in 2018 and with a CAGR if xx% between 2019-2025.

Product Type Coverage (Market Size & Forecast, Major Company of Product Type etc.):

- Fully Automatic
- Semi-Automatic
- Manual

Demand Coverage (Market Size & Forecast, Consumer Distribution):

- Integrated Device Manufacturers (IDMs)
- Outsourced Semiconductor Assembly and Test (OSAT)

Company Coverage (Sales data, Main Products & Services etc.):

- Besi
- ASM Pacific Technology (ASMPT)
- Kulicke & Soffa
- Palomar Technologies
- Shinkawa
- DIAS Automation
- Toray Engineering
- Panasonic
- FASFORD TECHNOLOGY
- West-Bond
- Hybond

Major Region Market

- North America
- Europe
- Asia-Pacific

South America

Middle East & Africa

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